



Practitioner's Docket No. U 013887-9

2811  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Intel application of: SUNG-FEI WANG, et al.  
Serial No.: 10/087,432  
Filed: March 1, 2002  
For: Stacked semiconductor chip package

Group No.: 2811  
Examiner: --

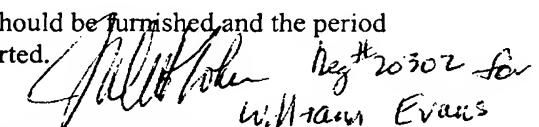
Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

REQUEST FOR COPY OF REFERENCE AND OR OTHER INFORMATION

RE: OFFICE ACTION

1. The Office Action mailed on July 30, 2003 has been received.
2. The Cited References \_\_\_\_\_  
[X] were not attached.  
[ ] were attached with pages missing.  
[ ] were incorrect: reference \_\_\_\_\_ was sent and is returned herewith.
3. Other:
4. It is requested that a copy of the cited reference should be furnished and the period allowed for response to the Office Action should be restarted.

Reg. No.: 25,858

  
Julian H. Cohen, Reg# 20302 for  
William R. Evans

SIGNATURE OF PRACTITIONER

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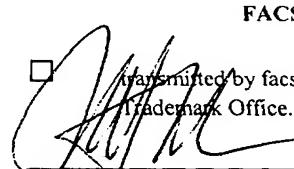
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Date: August 7, 2003

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